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SEMICONDUCTOR DEVICE

Inventor:	Shigeki Koto Matsushita Electric Industrial Co., Ltd. 1-1 Shiawase Mura Takatsuki-shi, Osaka
Applicant:	000005843 Matsushita Electric Industrial Co., Ltd. 1-1 Shiawase Mura Takatsuki-shi, Osaka
Agent:	Tsutomu Matsumura, patent attorney

[There are no amendments to this patent.]

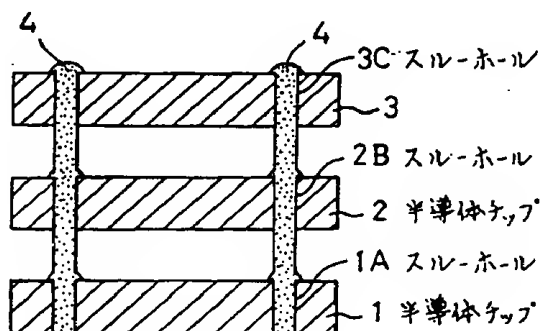
Abstract

Purpose

To realize an integrated circuit with high mounting density by stacking multiple semiconductor chips.

Constitution

Multiple semiconductor chips 1, 2, 3 are stacked at specific intervals and are electrically connected by means of conductive material 4 through through-holes 1A, 2B, 3C provided to the semiconductor chips.



Key: 1 Semiconductor chip
 1A Through-holes
 2 Semiconductor chip
 2B Through-holes
 3C Through-holes

Claim

A semiconductor device characterized in that multiple semiconductor chips having multiple through-holes are stacked at specific intervals by means of a conductive material in the through-holes, and said semiconductor chips are electrically connected.

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